



Electronics Assembly Process Control Kit (J-STD-001 / J-STD-033 / SMT)

Soldering process control, MSD floor-life tracking, solder paste and reflow logs, and rework traceability for EMS shops.

What's inside

File	What it is / how to use it
01_Electronics_Process_Control_Workbook.xlsx	Process control plan, MSD floor-life and bake log, dry cabinet log, paste control, reflow verification, iron/pot temperature log, proficiency matrix and rework log.
02_MSD_Control_Procedure.docx	MSD handling procedure.
03_Rework_Authorization_Form.docx	One-off authorization.
04_Process_Control_Procedure.docx	How the control plan is used.

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IPC and JEDEC standards are copyrighted. This kit does not reproduce floor-life tables, bake tables or acceptance criteria: you enter limits from the moisture barrier bag label, the paste or component datasheet, or your licensed copy. Not affiliated with IPC or JEDEC.

About the author

Built by Matt Norman, US Navy veteran and former SpaceX Falcon 9 quality inspector and QA supervisor. (Not affiliated with or endorsed by SpaceX.) Norman Quality Tools is Veteran-Owned & Operated. Contains no SpaceX, government, or customer proprietary information; all example data is made up.

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Moisture-Sensitive Device (MSD) Control Procedure

Electronics Assembly Process Control Kit (J-STD-001 / J-STD-033 / SMT) - Document 02 - Rev A (2026-10)

1. Purpose and scope

Prevent moisture damage (popcorning, delamination) to moisture-sensitive components at [Company], following IPC/JEDEC J-STD-033 (cited by number only).

2. Responsibilities

Role	Responsibility
Production supervisor	[Define]
Quality manager	[Define]

3. Procedure

- Receiving: check bag seal, humidity indicator card and label; record MSL and floor life from the label.
- On opening, log the reel in the MSD Floor Life tracker with the open time.
- Return unused parts to dry storage or reseal with fresh desiccant and HIC; record exposure.
- Never use a part with negative hours left; bake per the label or your licensed J-STD-033, and log the bake.
- Check dry cabinet RH every shift.
- Train operators; audit monthly.

4. Records

- MSD Floor Life
- Bake Log
- Dry Cabinet log

5. Revision history

Rev	Date	Change	Approved

Role	Name	Signature	Date
Prepared by			
Approved by			

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